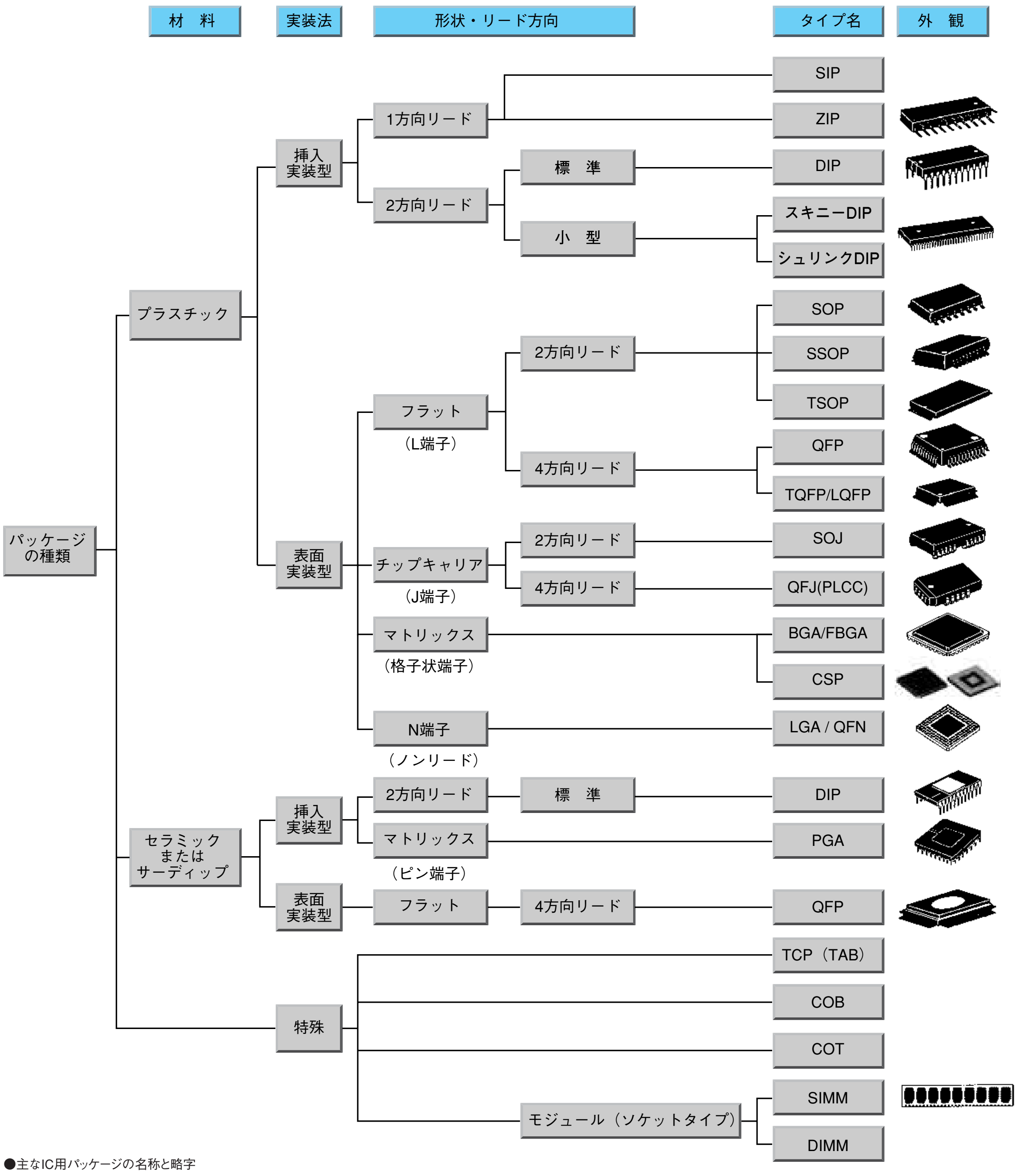
図2-4-1　主なIC用パッケージの種類



●主なIC用パッケージの名称と略字

BGA：Ball Grid Array
COB：Chip On Board
COT：Chip On Tape
CSP：Chip Size Package/Chip Scale Package
DIMM：Dual In-line Memory Module
DIP：Dual In-line Package
FBGA：Fine-pitch Ball Grid Array
FLGA：Fine-pitch Land Grid Array（CSPの一種）
FQFP：Fine-pitch Quad Flat Package
HSIP：Single In-line Package with Heatsink
LCC：Leadless Chip Carrier
LFLGA：Low profile Fine pitch Land Grid Array
LGA：Land Grid Array
LQFP：Low-profile Quad Flat Package
MC-FBGA：Multi-Chip Fine-pitch Ball Grid Array
MCM：Multi-Chip Module
MCP：Multi-Chip Package
M-CSP：Molded Chip Size Package
MFP：Mini Flat Package（SOPの一種）
MQFP：Metric Quad Flat Package（QFP）
MQUAD：Metal Quad（QFPの一種）
MSOP：Micro Small Outline Package
PGA：Pin Grid Array
PLCC：Plastic Leaded Chip Carrier（QFJの一種）
PLCC：Plastic Leadless Chip Carrier（QFNの一種）
QFI：Quad Flat I-leaded Package
QFJ：Quad Flat J-leaded Package
QFN：Quad Flat non-leaded Package（QFPの一種）
QFP：Quad Flat Package
QTCP：Quad Tape Carrier Package
QUIP:Quad In-line Package
SDIP：Shrink Dual In-line Package
SIMM：Single In-line Memory Module
SIP：Single In-line Package
S-MCP：Stacked Multi Chip Package
SNB：Small Outline Non-leaded Board Package(CSPの一種)
SOI：Small Outline I-leaded Package
SOJ：Small Outline J-leaded Package
SON：Small Outline Non-leaded Package
SOP：Small Outline Package
SSIP：Shrink Single In-line Package
SSOP：Shrink Small Outline Package
SZIP：Shrink Zigzag In-line Package
TAB：Tape-Automated Bonding
TCP：Tape Carrier Package
TQFP：Thin Quad Flat Package
TSOP：Thin Small Outline Package
TSSOP：Thin Shrink Small Outline Package
UCSP：Ultra Chip Scale Package
UTSOP：Ultra Thin Small Outline Package
VSO：Very Short Pitch Small Outline Package（SSOP）
VSOP：Very Small Outline Package（小型SOP）
W-CSP：Wafer Level Chip Size Package
ZIP：Zigzag In-line Package
μMCP：Micro Multi-Chip Package